

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJAB25P03H
Package Type :	PDFNWB3.3x3.3-8L

2. MATERIAL ANALYSIS DATA SHEET

Material	Composition	CAS No.	% of weight	% of weight total
Wafer	Silicon	7440-21-3	100.00%	4.80%
Lead Frame	Copper	7440-50-8	97.342%	30.5102%
	Iron	7439-89-6	2.40%	
	Zinc	7440-66-6	0.15%	
	Phosphorus	7723-14-0	0.10%	
	Lead (Pb)	7439-92-1	0.008%	
	Silver	7440-22-4	2.50%	
Die Attach	Lead	7439-92-1	83.45%	3.9674%
	Tin	7440-31-5	4.50%	
	Silver	7440-22-4	2.15%	
	Butanediol mixture	107-88-0	8.50%	
	Modified castor oil	61788-85-0	1.40%	
Wire	Copper	7440-50-8	99.997%	9.1864%
	Others	/	0.003%	
Mold Compound	Silica	60676-86-0	86.45%	42.1407%
	Epoxy Resin	85954-11-6	6.50%	
	Phenol Resin	26834-02-6	6.50%	
	Carbon black	1333-86-4	0.55%	
Plating	Tin	7440-31-5	99.99%	9.3953%
	Other	/	0.01%	

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.